Central Semiconductor Corp.
145 Adams Avenue, Hauppauge, NY 11788 USA
Tel: (631) 435-1110 • Fax: (631) 435-1824
www.centralsemi.com
mailto:processchange@centralsemi.com
http://www.centralsemi.com/processchange

PCN #: 113
Notification Date:
25 May 2010

Process Change Notice

Parts Affected:
All discrete semiconductor devices manufactured in the SOD-123, SOT-23, and SOT-323 packages.

Extent of Change:
Copper wire has been added as a qualified material for wire bonding in addition to the currently used gold wire.

Reason for Change:
This change will insure an uninterrupted flow of product and provide increased flexibility for supply chain management.

Effect of Change:
This change does not affect the form, fit, or function of any device. Devices assembled with gold wire will continue to be manufactured concurrently with devices assembled with copper wire.

Qualification:
Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:
August 1, 2010.

Sample Availability:
Please contact Salesperson or Manufacturer's Representative.